DuPont™ PlasmaSolv®
EKC270™
Post-Etch Residue Remover

DuPont™ PlasmaSolv® EKC270™ post-etch residue remover is made with DuPont™ HDA® hydroxylamine technology for enhanced performance.

Benefits
• Formulated for optimum metal stack integrity
• “Improved” wide window process capability
• Enhanced post etch residue removal
• Patented and patent pending improved reduction chemistry
• Ultra Large Scale Integration (ULSI) grade specifications for advanced wafer cleaning
• Low evaporation rate at operating temperature

Figure 1. DuPont™ PlasmaSolv® EKC270™ demonstrates superior performance, even under aggressive processing conditions (75 °C for 50 min)

1a. Conventional Remover

1b. DuPont™ EKC270™

Super Clean; Maintaining Metal Integrity

Corrosion
Al Attack
For more information on DuPont™ PlasmaSolv® EKC270™ or other DuPont products, please visit our website.

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